



CRTM035N04L2-G

General Description:

CRTM035N04L2-G, the silicon N-channel Enhanced VDMOSFETs, is obtained by the high density Trench technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. This device can be used in load switch and power switch applications. The package form is PDFN5*6, which accords with the RoHS standard.

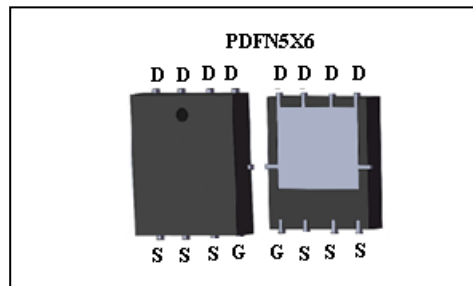
Features:

- Fast Switching
- Low ON Resistance ($R_{DS(on)} \leq 3.4m\Omega$)
- Low Gate Charge
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test
- Halogen Free

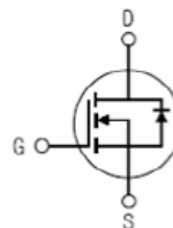
Applications:

load switch and power switch applications.

V_{DSS}	40	V
I_D (Silicon limited current)	130	A
I_D (Package limited current)	60	A
P_D	104.1	W
$R_{DS(ON)Typ}$	2.7	m Ω



Inner Equivalent Principium Chart

**Absolute** ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	40	V
I_D	Continuous Drain Current $T_C = 25^\circ\text{C}$	130	A
	Continuous Drain Current $T_C = 25^\circ\text{C}$ (Package limited)	60	A
	Continuous Drain Current $T_C = 100^\circ\text{C}$ (Package limited)	60	A
I_{DM}^{a1}	Pulsed Drain Current $T_C = 25^\circ\text{C}$	240	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}^{a2}	Avalanche Energy	282.2	mJ
P_D	Power Dissipation $T_C = 25^\circ\text{C}$	104.1	W
	Derating Factor above 25°C	0.83	W/ $^\circ\text{C}$
T_J, T_{stg}	Operating Junction and Storage Temperature Range	150, -55 to 150	$^\circ\text{C}$

Electrical Characteristics (T_J= 25℃ unless otherwise specified):

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V _{DSS}	Drain to Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	40	--	--	V
I _{DSS}	Drain to Source Leakage Current	V _{DS} = 40V, V _{GS} = 0V, T _J = 25℃	--	--	1	μA
		V _{DS} =32V, V _{GS} = 0V, T _J = 125℃	--	--	100	
I _{GSS(F)}	Gate to Source Forward Leakage	V _{GS} =+20V	--	--	100	nA
I _{GSS(R)}	Gate to Source Reverse Leakage	V _{GS} =-20V	--	--	-100	nA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R _{DS(ON)}	Drain-to-Source On-Resistance	V _{GS} =10V,I _D =19A	--	2.7	3.4	mΩ
		V _{GS} =4.5V,I _D =19A	--	3.6	4.5	mΩ
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1	1.4	2	V
Pulse width tp ≤ 300μs, δ ≤ 2%						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R _g	Gate resistance	V _{GS} =0V,V _{DS} =0V,f=1MHz	--	2.1	--	Ω
C _{iss}	Input Capacitance	V _{GS} = 0V V _{DS} =20V f = 1.0MHz	--	3312	--	pF
C _{oss}	Output Capacitance		--	324	--	
C _{rss}	Reverse Transfer Capacitance		--	310	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
t _{d(ON)}	Turn-on Delay Time	V _{GS} =10V, R _G =3Ω V _{DD} =20V, I _D =19A	--	14.8	--	ns
t _r	Rise Time		--	28.4	--	
t _{d(OFF)}	Turn-Off Delay Time		--	70.6	--	
t _f	Fall Time		--	18.8	--	
Q _g	Total Gate Charge	I _D =19A V _{DD} =20V V _{GS} = 10V	--	68.3	--	nC
Q _{gs}	Gate to Source Charge		--	8.7	--	
Q _{gd}	Gate to Drain ("Miller")Charge		--	15	--	

Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I_S	Continuous Source Current (Body Diode)	$T_C = 25^\circ\text{C}$	--	--	60	A
I_{SM}	Maximum Pulsed Current (Body Diode)		--	--	240	A
V_{SD}	Diode Forward Voltage	$I_S=19\text{A}, V_{GS}=0\text{V}$	--	--	1.2	V
t_{rr}	Reverse Recovery Time	$di/dt=100\text{A}/\mu\text{s}$	--	38.2	--	ns
Q_{rr}	Reverse Recovery Charge	$I_S=19\text{A}$	--	25.6	--	nC
Pulse width $t_p \leq 300\mu\text{s}$, $\delta \leq 2\%$						

Symbol	Parameter	Max.	Units
$R_{\theta JC}$	Junction-to-Case	1.2	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient	62.5	$^\circ\text{C}/\text{W}$

Notes:

- ^{a1}: Repetitive rating; pulse width limited by maximum junction temperature
^{a2}: $L=0.5\text{mH}$, $I_D=33.6\text{A}$, Start $T_J=25^\circ\text{C}$
^{a3}: Recommend soldering temperature defined by IPC/JEDEC J-STD 020

Characteristics Curve:

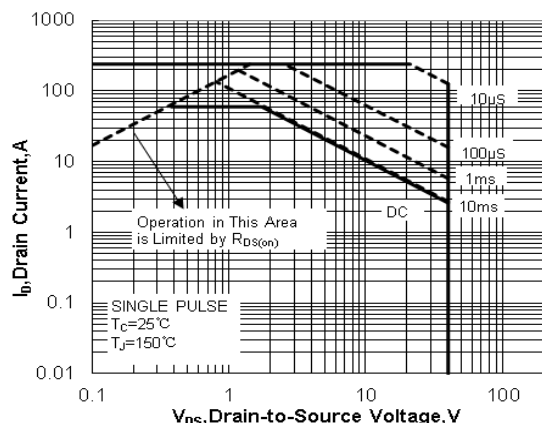


Figure 1 . Maximum Safe Operating Area

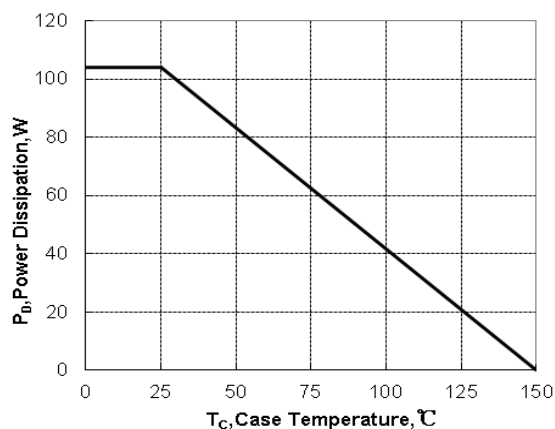


Figure 2. Maximum Power Dissipation vs Case Temperature

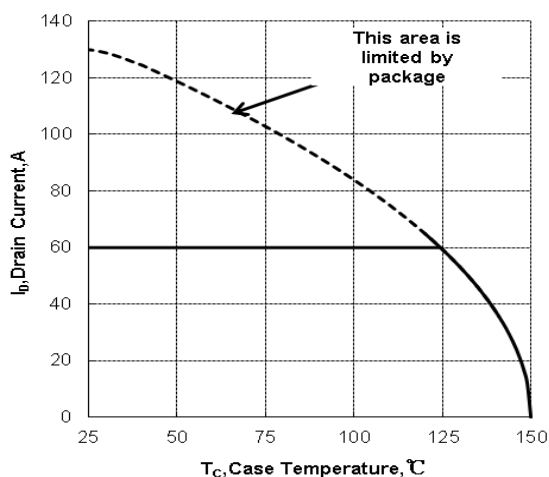


Figure 3. Maximum Continuous Drain Current vs Case Temperature

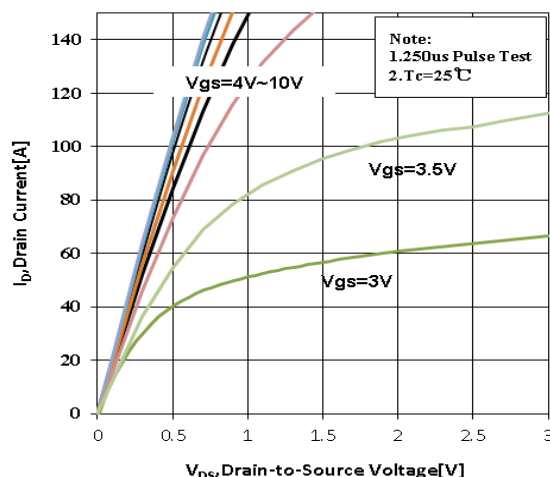


Figure 4. Typical output Characteristics

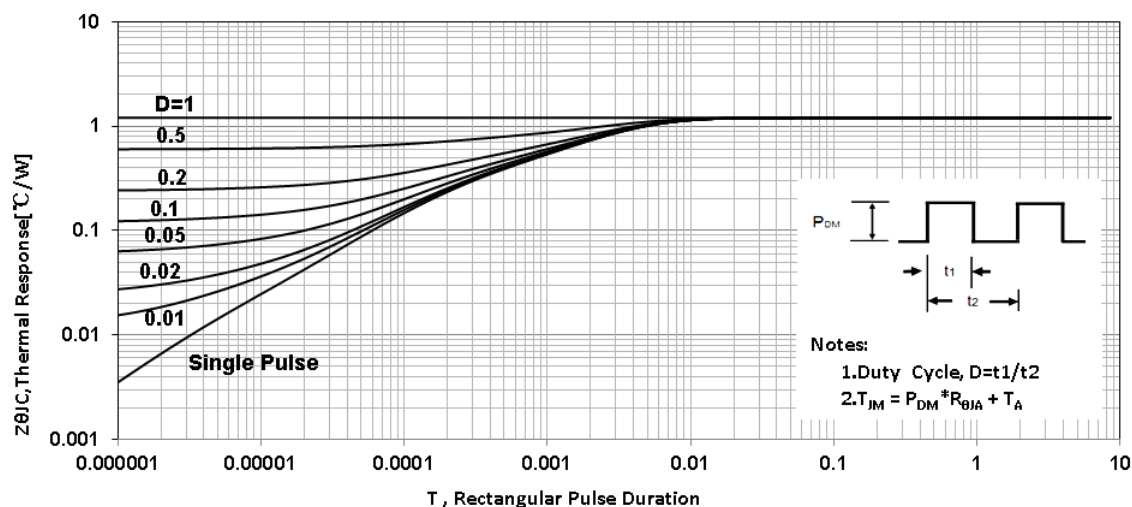


Figure 5 Maximum Effective Thermal Impedance , Junction to Case

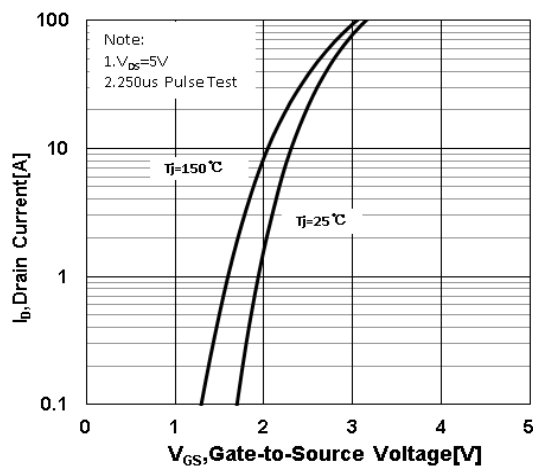


Figure 6 Typical Transfer Characteristics

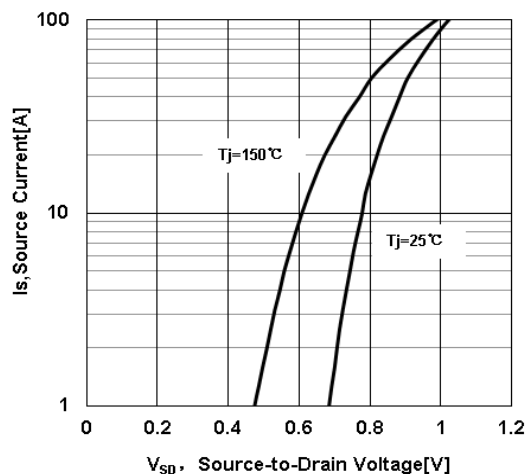


Figure 7 Typical Body Diode Transfer Characteristics

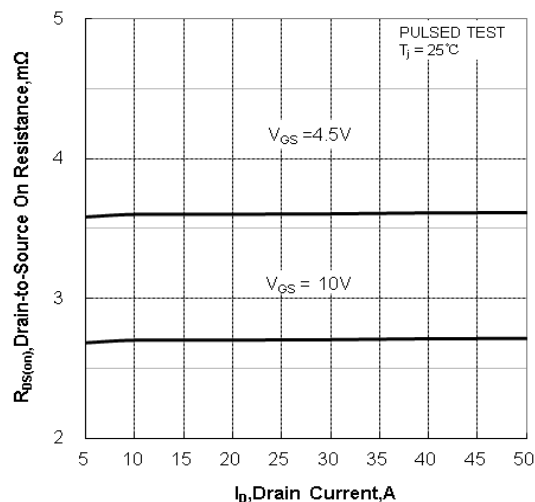


Figure 8. Drain-to-Source On Resistance vs Drain Current

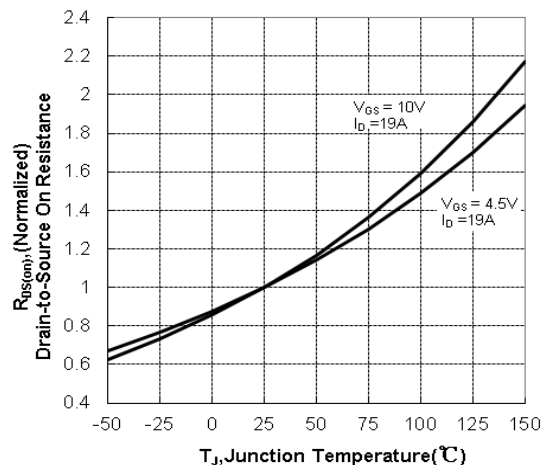


Figure 9. Normalized On Resistance vs Junction Temperature

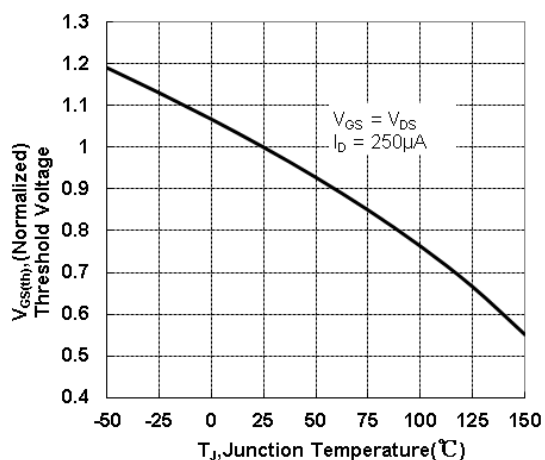


Figure10. Normalized Threshold Voltage vs Junction Temperature

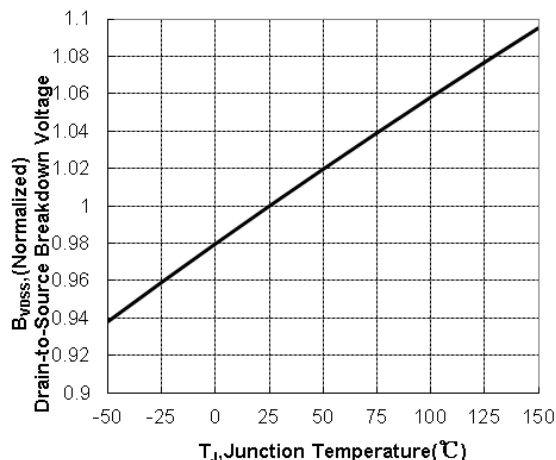


Figure 11. Normalized Breakdown Voltage vs Junction Temperature

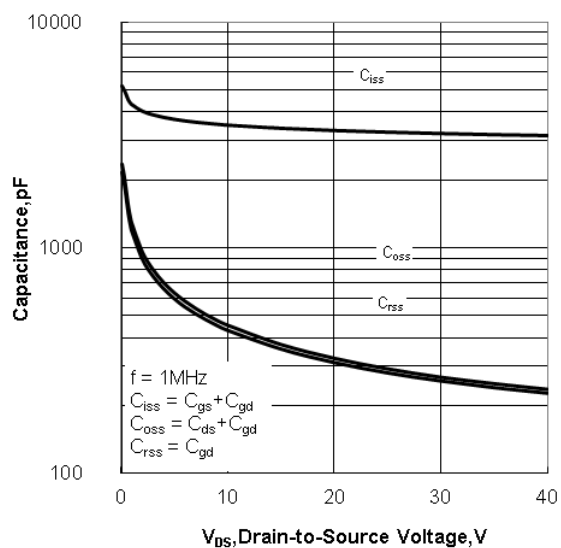


Figure 12. Capacitance Characteristics

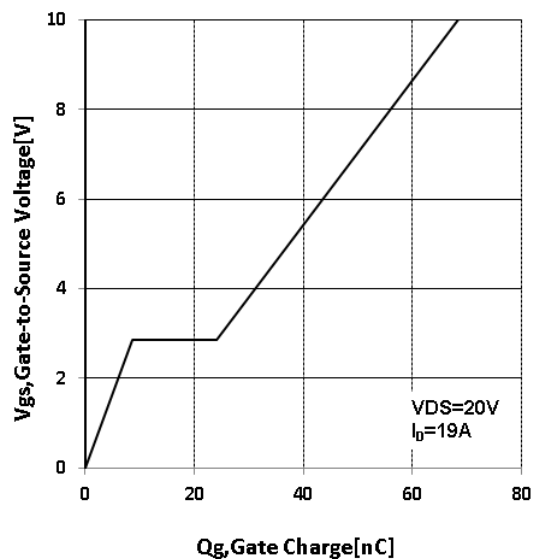


Figure 13 Typical Gate Charge vs Gate to Source Voltage

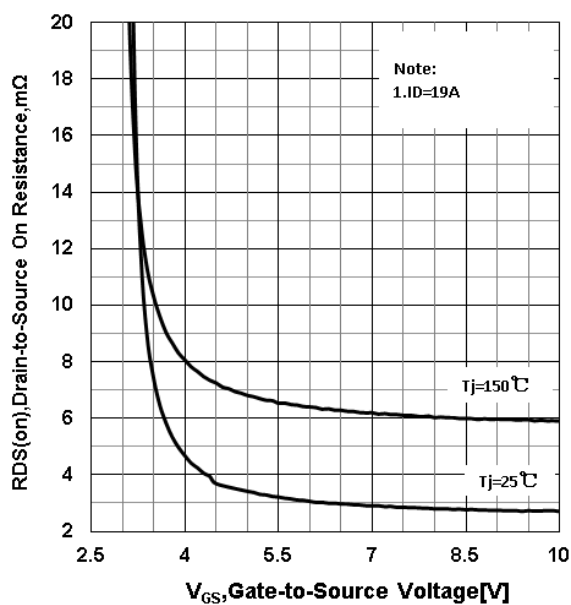


Figure 14 . Drain-to-Source On Resistance vs Gate Voltage

Test Circuit and Waveform:

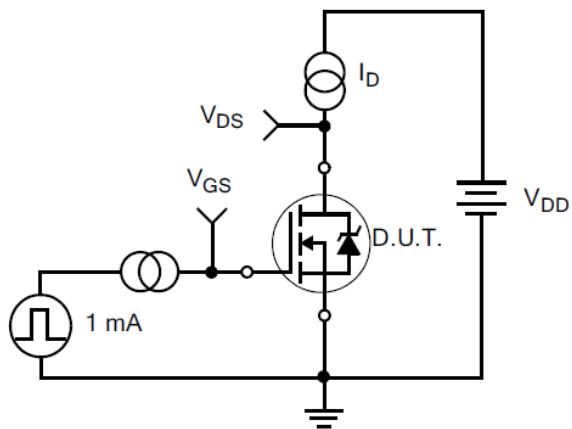


Figure 15. Gate Charge Test Circuit

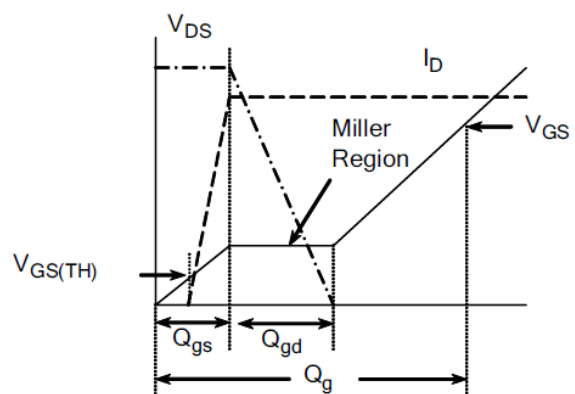


Figure 16. Gate Charge Waveforms

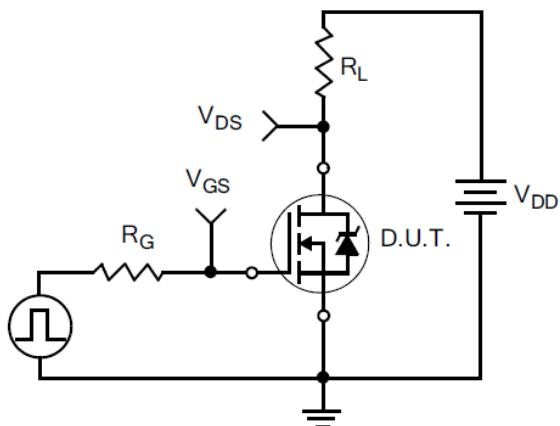


Figure 17. Resistive Switching Test Circuit

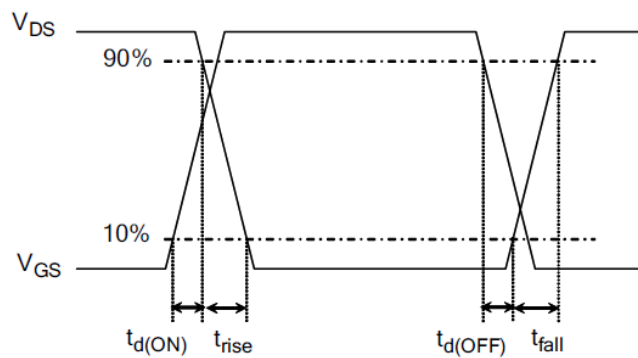


Figure 18. Resistive Switching Waveforms

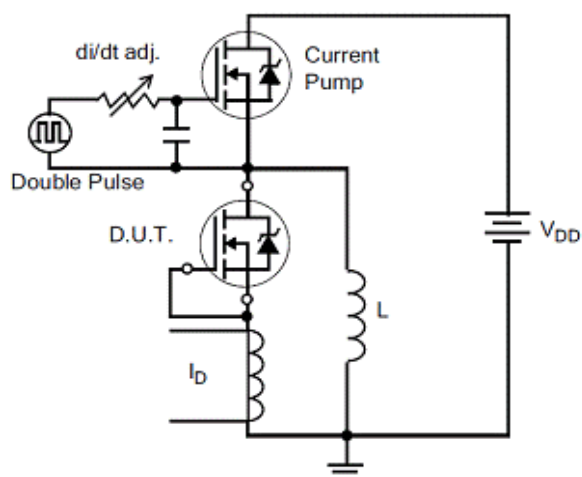


Figure 19. Diode Reverse Recovery Test Circuit

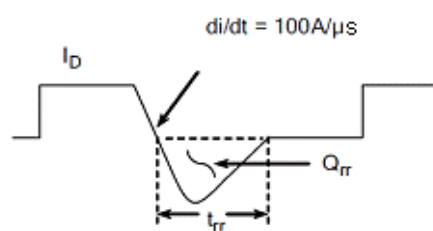


Figure 20. Diode Reverse Recovery Waveform

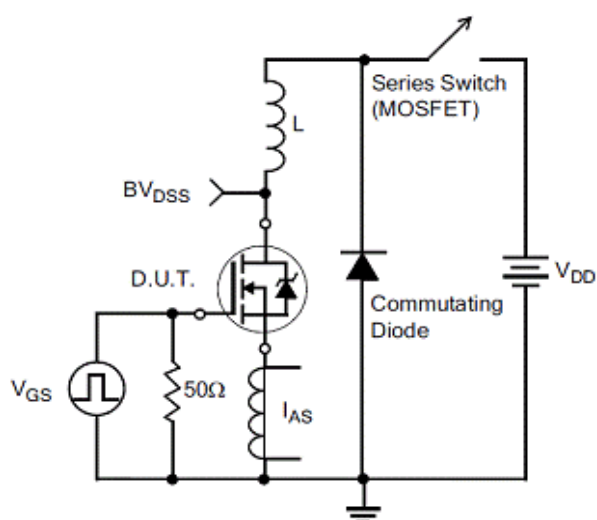


Figure21.Unclamped Inductive Switching Test Circuit

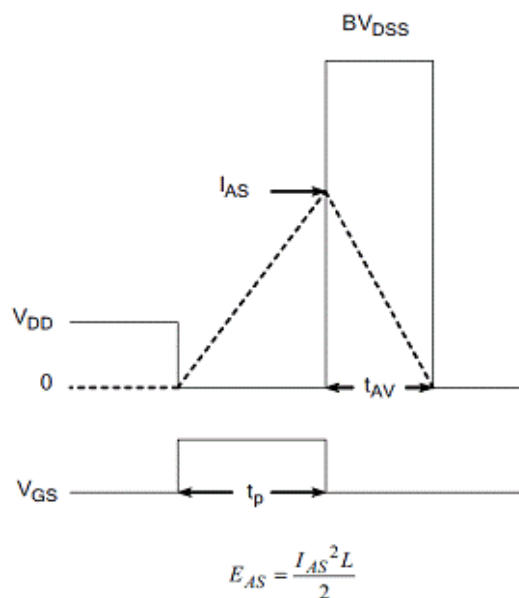
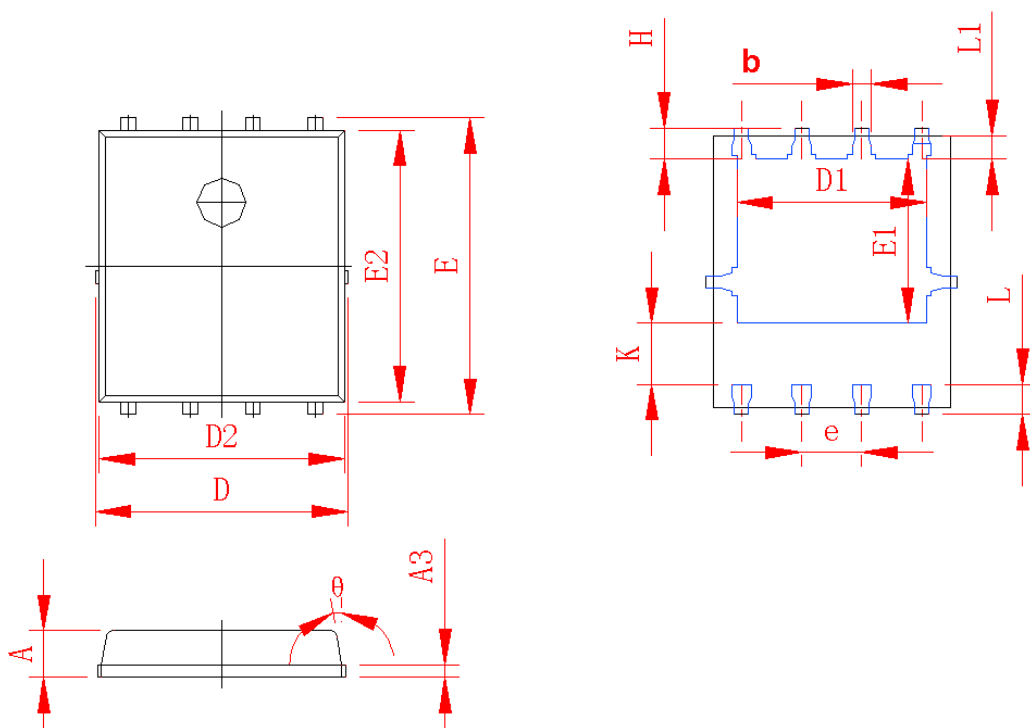


Figure22.Unclamped Inductive Switching Waveform



Symbol	Values(mm)	
	MIN	MAX
A	0.70	1.20
A3	0.15	0.35
D	4.85	5.35
E	5.77	6.32
D1	3.81	4.40
E1	3.33	3.90
D2	4.72	5.30
E2	5.57	6.05
k	1.09	1.50
b	0.20	0.60
e	1.07	1.47
L	0.40	0.82
L1	0.35	0.65
H	0.35	0.85
θ	8 °	12 °

PDFN5×6 Package

The name and content of poisonous and harmful material in products

Part's Name	Hazardous Substance									
	Pb	Hg	Cd	Cr (VI)	PBB	PBDE	DIBP	DEHP	DBP	BBP
Limit	≤ 0.1%	≤ 0.1%	≤ 0.01%	≤0.1%	≤ 0.1%	≤0.1%	≤0.1%	≤0.1%	≤0.1%	≤0.1%
Lead Frame	○	○	○	○	○	○	○	○	○	○
Molding	○	○	○	○	○	○	○	○	○	○
Chip	○	○	○	○	○	○	○	○	○	○
Wire Bonding	○	○	○	○	○	○	○	○	○	○
Solder	×	○	○	○	○	○	○	○	○	○
Note	○: Means the hazardous material is under the criterion of 2011/65/EU. ×: Means the hazardous material exceeds the criterion of 2011/65/EU. The plumbum element of solder exist in products presently, but within the allowed range of Eurogroup's RoHS.									

Warnings

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. It is suggested to be used under 80 percent of the maximum ratings of the d
2. evice.
3. When installing the heat sink, please pay attention to the torsional moment and the smoothness of the heat sink.
4. VDMOSFETs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
5. This publication is made by Huajing Microelectronics and subject to regular change without notice.

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